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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10051906	01/16/2002	430	311 5	1756	Ruggles

****APPLICANTS:** Su Chao-Yuan; Lin Chia-Fu; Lee Hsin-Hui; Chen Yen-Ming;
Ching Kai-Ming; Chen Li-Chih;

****CONTINUING DATA VERIFIED:**

**** FOREIGN APPLICATIONS VERIFIED:**

PG-PUB ☐ DO NOT PUBLISH ☐RESCIND ☐Foreign priority claimed ☐ yes ☐ no35 USC 119 conditions met ☐ yes ☐ no

Verified and Acknowledged Examiners's initials

ATTORNEY DOCKET NO

67,200-630

TITLE : Method of forming a solder ball using a thermally stable resinous protective layer

U.S. DEPT. OF COMM./PAT. & TM.-PTO-436L (Rev. 12-94)

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NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg.
		Print Fig.	
<input type="checkbox"/> TERMINAL DISCLAIMER		Primary Examiner	
		Prepared for Issue	
		Applicant's Examiner	
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